

RF2192

3V 900MHZ LINEAR POWER AMPLIFIER

Typical Applications

- 3V CDMA/AMPS Cellular Handsets
- 3V JCDMA Cellular Handsets
- 3V CDMA2000 Cellular Handsets
- 3V TDMA/GAIT Cellular Handsets
- Spread-Spectrum Systems
- Portable Battery-Powered Equipment

Product Description

The RF2192 is a high-power, high-efficiency linear amplifier IC targeting 3V handheld systems. The device is manufactured on an advanced Gallium Arsenide Heterojunction Bipolar Transistor (HBT) process, and has been designed for use as the final RF amplifier in dual-mode 3V CDMA/AMPS and CDMA2000 handheld digital cellular equipment, spread-spectrum systems, and other applications in the 800MHz to 960MHz band. The RF2192 has a low power mode to extend battery life under low output power conditions. The device is packaged in a 16 pin, 4mmx4mm leadless chip carrier.

Optimum Technology Matching® Applied

GaAs HBT

SiGe HBT

ò

16

vcc

15

GaAs MESFET

Si CMOS

2F0

12

11

RF OUT

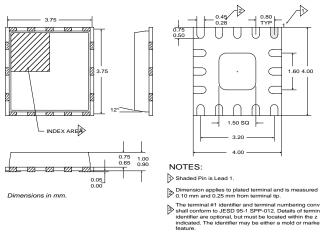
RF OUT

BIAS

202

14 13

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Pins 1 and 9 are fused.
Package Warpage: 0.05 max.

Package Style: LCC, 16-Pin, 4x4

Features

- Single 3V Supply
- 29dBm Linear Output Power
- 37% Linear Efficiency
- Low Power Mode
- 45 mA idle current
- 47% Peak Efficiency 31 dBm Output

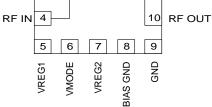
Ordering Information RF2192 3V 900MHz Linear Power Amplifier RF2192 PCBA Fully Assembled Evaluation Board RF Micro Devices, Inc. Tel (336) 664 1233 7628 Thorndike Road Fax (336) 664 0454 Greensboro, NC 27409, USA http://www.rfmd.com 2

GND 2

GND 3

UND UD

1

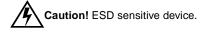


Si BJT

Si Bi-CMOS

Absolute Maximum Ratings

0					
Parameter	Rating	Unit			
Supply Voltage (RF off)	+8.0	V _{DC}			
Supply Voltage (P _{OUT} ≤31dBm)	+5.2	V _{DC}			
Mode Voltage (V _{MODE})	+4.2	V _{DC}			
Control Voltage (V _{REG})	+3.0	V _{DC}			
Input RF Power	+10	dBm			
Operating Case Temperature	-30 to +110	°C			
Storage Temperature	-30 to +150	°C			
Moisture Sensitivity	Modified JEDEC Level 2				



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Parameter		Specification		Unit	Condition	
Farameter	Min.	Тур.	Max.	Unit	Condition	
High Power State (V _{MODE} Low)					Case T=25°C, V_{CC} =3.4V, V_{REG} = 2.85V, V_{MODE} =0V to 0.5V, Freq=824MHz to 849MHz (unless otherwise specified)	
Frequency Range	824		849	MHz		
Linear Gain	27	30		dB		
Second Harmonic		-33		dBc		
Third Harmonic		<-60		dBc		
Maximum Linear Output Power (CDMA Modulation)	29			dBm		
Total Linear Efficiency		37		%	P _{OUT} =29dBm	
Adjacent Channel Power Rejec- tion		-48	-44	dBc	ACPR @ 885kHz	
		-58	-56	dBc	ACPR @ 1980kHz	
Input VSWR		2:1				
Output VSWR			10:1		No damage.	
			6:1		No oscillations. >-70dBc	
Noise Power		-133		dBm/Hz	At 45MHz offset	
Low Power State					Case T=25 °C, V _{CC} =3.4V, V _{REG} =2.85V,	
(V _{MODE} High)					V _{MODE} =1.8V to 3V, Freq=824MHz to	
(MODE					849MHz (unless otherwise specified)	
Frequency Range	824		849	MHz		
Linear Gain	19	22		dB		
Second Harmonic		-33		dBc		
Third Harmonic		<-60		dBc		
Maximum Linear Output Power (CDMA Modulation)	16	20		dBm		
Max I _{CC}		150		mA	P _{OUT} =+16dBm (all currents included)	
Adjacent Channel Power Rejec- tion		-48	-46	dBc	ACPR @ 885kHz	
		<-60	-58	dBc	ACPR @ 1980kHz	
Input VSWR		2:1				
Output VSWR			10:1		No damage.	
			6:1		No oscillations. >-70dBc	

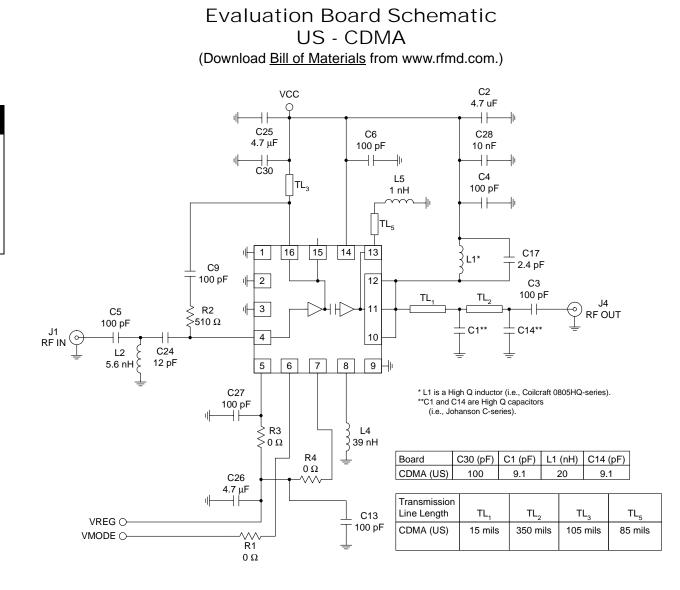
RF2	21	9	2

Devenuetor		Specification		11	O an ditian	
Parameter	Min.	Тур.	Max.	Unit	Condition	
High Power State CDMA 2000 1x (V _{MODE} LOW)					Case T=25°C, V_{CC} =3.4V, V_{REG} =2.85V. V_{MODE} =0V to 0.5V, Freq=824MHz to 849MHz (unless otherwise specified)	
Frequency Range Linear Gain Pilot+DCCH 9600	824	29	849	MHz dB		
Maximum Linear Output Power (CDMA 2000 Modulation)	26.5			dBm	2.5dB Backoff included in IS98D CCDF 1% 5.4dB Peak Average Ratio at CCDF 1%	
Adjacent Channel Power Rejec- tion		-47		dBc	ACPR @ 885 kHz	
Pilot+FCH 9600+SCHO 9600		<-60		dBc	ACPR @ 1.98MHz	
Maximum Linear Output Power (CDMA 2000 Modulation)	29			dBm	4.5dB Peak Average Ratio at CCDF 1%	
Adjacent Channel Power Rejec- tion		-47		dBc	ACPR @ 885 kHz	
		<-60		dBc	ACPR @ 1.98MHz	
Low Power State CDMA 2000 1x (V _{MODE} HIGH)					Case T=25°C, V_{CC} =3.4V, V_{REG} =2.85V. V_{MODE} =1.8V to 3V, Freq=824MHz to 849MHz	
Frequency Range Linear Gain Pilot+DCCH 9600	824	22	849	MHz dB		
Maximum Linear Output Power (CDMA 2000 Modulation)	16	20		dBm	5.4dB Peak to Average Ratio at CCDF 1%	
Adjacent Channel Power Rejec- tion		-48		dBc	ACPR @ 885 kHz	
		<-85		dBc	ACPR @ 1.98MHz	
Efficiency Pilot+FCH 9600+SCHO 9600		15		%	P _{OUT} =20dBm	
Maximum Linear Output Power (CDMA 2000 Modulation)	16	20		dBm	4.5dB Peak to Average Ratio at CCDF 1%	
Adjacent Channel Power Rejec- tion		<-50		dBc	ACPR @ 885 kHz	
		<-65		dBc	ACPR@1.98MHz	
FM Mode					Case T=25°C, V_{CC} =3.4V, V_{REG} =2.85V, V_{MODE} =0V to 0.5V, Freq=824MHz to 849MHz (unless otherwise specified)	
Frequency Range	824		849	MHz		
Gain Second Harmonic		30 -33		dB dBc		
Third Harmonic		-33 <-60		dBc		
Max CW Output Power	31	32		dBm		
Total Efficiency (AMPS mode)		47		%	P _{OUT} =31 dBm (room temperature)	
Input VSWR		2:1	10:1			
Output VSWR			10:1 6:1		No damage. No oscillations. >-70dBc	

Note: DCCH: Dedicated Control Channel FCH: Fundamental Channel CCDF: Complementary Cumulative Distribution Function

Deremeter		Specificatior	1	110:4	Condition	
Parameter	Min.	Тур.	Max.	Unit		
DC Supply						
Supply Voltage	3.0	3.4	4.2	V	The maximum power out for V_{CC} =3.0V is	
					28dBm.	
Quiescent Current		160		mA	V _{MODE} =Low	
		45	70	mA	V _{MODE} =High	
V _{REG} Current			10	mA		
V _{MODE} Current			1	mA		
Turn On/Off Time			<40	μs	Time between V _{REG} turned on and PA	
					reaching full power. Turn on/off time can be	
					reduced by lowering the bypass capacitor	
					value on the V _{REG} line.	
Total Current (Power Down)			10	μA	V _{REG} =Low	
V _{REG} "Low" Voltage	0		0.5	V		
V _{REG} "High" Voltage	2.75	2.85	2.95	V		
V _{MODE} "Low" Voltage	0		0.5	V		
V _{MODE} "High" Voltage	1.8	2.85	3.0	V		

Pin	Function	Description	Interface Schematic
1	GND	Ground connection.	
2	GND	Ground connection.	
3	GND	Ground connection.	
4	RF IN	RF input. An external 100pF series capacitor is required as a DC block. In addition, shunt inductor and series capacitor are required to provide 2:1VSWR.	VCC1 100 pF RF INO Front Bias GND1 Stages
5	VREG1	Power Down control for first stage. Regulated voltage supply for amplifier bias. In Power Down mode, both V_{REG} and V_{MODE} need to be LOW (<0.5 V).	
6	VMODE	For nominal operation (High Power Mode), V_{MODE} is set LOW. When set HIGH, the driver and final stage are dynamically scaled to reduce the device size and as a result to reduce the idle current.	
7	VREG2	Power Down control for the second stage. Regulated voltage supply for amplifier bias. In Power Down mode, both V_{REG} and V_{MODE} need to be LOW (<0.5V).	
8	BIAS GND	Bias circuitry ground. See application schematic.	
9	GND	Ground connection.	
10	RF OUT	RF output and power supply for final stage. This is the unmatched col- lector output of the second stage. A DC block is required following the matching components. The biasing may be provided via a parallel L-C set for resonance at the operating frequency of 824MHz to 849MHz. It is important to select an inductor with very low DC resistance with a 1A current rating. Alternatively, shunt microstrip techniques are also appli- cable and provide very low DC resistance. Low frequency bypassing is required for stability.	RF OUT
11	RF OUT	Same as pin 10.	See pin 10.
12	RF OUT	Same as pin 10.	
13	2FO	Harmonic trap. This pin connects to the RF output but is used for pro- viding a low impedance to the second harmonic of the operating fre- quency. An inductor or transmission line resonating with an on chip capacitor at 2fo is required at this pin.	
14	VCC BIAS	Power supply for bias circuitry. A 100pF high frequency bypass capacitor is recommended.	
15	VCC1	Power supply for first stage.	
16	VCC1	Same as Pin 15.	
Pkg Base	GND	Ground connection. The backside of the package should be soldered to a top side ground pad which is connected to the ground plane with mul- tiple vias. The pad should have a short thermal path to the ground plane.	



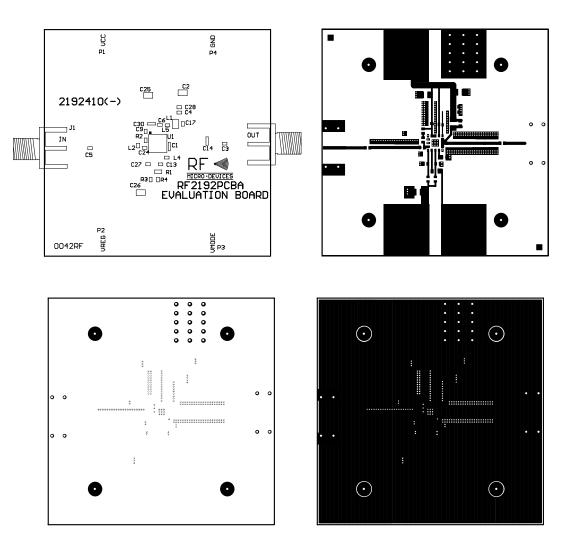
RF2192

Rev A1 010830



Evaluation Board Layout 2.0" x 2.0"

Board Thickness 0.031", Board Material FR-4, Multi-Layer, Ground Plane at 0.015"



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